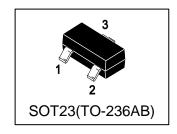


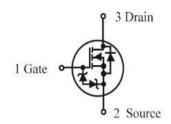
# LNTR4003NLT1G S-LNTR4003NLT1G

30 V, 0.56 A, Single, N-Channel, Gate ESD Protection, SOT-23



#### 1. FEATURES

- Low gate voltage threshold(VGS(th))to facilitate drive circuit design
- Low gate charge for fast switching
- ESD protected gate
- Minimum breakdown voltage rating of 30 V
- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.



# 2. APPLICATIONS

- Level shifters
- Level switches
- Low side load switches
- Portable applications

#### 3. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LNTR4003NLT1G	TR8	3000/Tape&Reel
LNTR4003NLT3G	TR8	10000/Tape&Reel

# 4. MAXIMUM RATINGS(Ta = 25°C)

Parame	Symbol	Limits	Unit	
Drain-Source Voltage		VDSS	30	V
Gate-to-Source Voltage	e – Continuous	VGS	±20	V
Current (Note 1)	TA = 25°C	ID	0.5	Α
Steady State	TA = 85°C		0.37	
Continuous Drain	TA = 25°C		0.56	
Current (Note 1) t<10s	TA = 85°C		0.4	
Pulsed Drain Current(tp=10µs)		IDM	1.7	Α
Continuous Source Current (Body Diode)		IS	1	Α
Maximum Power Dissipation(Note 1)		PD		W
Steady State			0.69	
t<5s		0.83		
Junction and Storage temperature		TJ,Tstg	<b>-</b> 55∼+150	°C
Maximum Temperature for Soldering		TL		°C
Purposes			260	

# LNTR4003NLT1G, S-LNTR4003NLT1G

30 V, 0.56 A, Single, N-Channel, Gate ESD Protection, SOT-23

#### 5. THERMAL CHARACTERISTICS

Parameter	Symbol	Limits	Unit
Thermal Resistance, Junction-to-Ambient	RΘJA		°C/W
Steady State(Note 1)		180	
t < 10s(Note 1)		150	

# 6. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

## **OFF CHARACTERISTICS**

Characteristic		Symbol	Min.	Тур.	Max.	Unit
Drain-Source Breakdo	own Voltage	V(BR)DSS				V
$(VGS = 0, ID = 100\mu A)$	)	V(BK)D33	30	-	-	
Drain-to-Source Brea	kdown Voltage	V(BR)DSS/				mV/°C
Temperature Coefficie	ent	TJ	-	40	-	
Zero Gate Voltage Dra	ain Current	IDSS				μA
(VDS=30V, VGS=0V)		1033	-	-	1.0	
Gate-Body Leakage C	Current, Forward	IGSS				μA
$(VDS = 0 V, VGS = \pm 1)$	0 V)	1633	-	-	±1.0	
ON CHARACTERISTIC	S (Note 2)					
Gate Threshold Voltag	je	VGS(th)				V
(VDS = VGS, ID = 250	)μΑ)	VG3(III)	8.0	-	1.6	
Negative Threshold Te	emperature Coefficient	VGS(TH)/TJ	-	3.4	-	mV/°C
Static Drain-Source O	n–State Resistance	RDS(on)				Ω
(VGS = 4.0 V, ID = 10	mA)		-	1	1.5	
(VGS = 2.5 V, ID = 10	mA)		-	1.5	2	
Forward Transconductance (VDS = 3.0 V, ID = 10 mA)		gfs -				S
			-	0.33	-	
YNAMIC CHARACTER	RISTICS					
Input Capacitance		Ciss				pF
(VGS = 0 V, f = 1.0MH)	Iz,VDS= 5 V)	Clss	-	41	-	
Output Capacitance		Coss				pF
(VGS = 0 V, f = 1.0MHz, VDS= 5 V)		Coss	-	12	-	
Reverse Transfer Capacitance		Crss				pF
(VGS = 0 V, f = 1.0MHz,VDS= 5 V)			-	8.1	<u>-</u>	
WITCHING CHARACT	ERISTICS					
Turn-On Delay Time	()(00 45)()(00 50	td(on)	-	16.7	-	ns
Rise Time	(VGS = 4.5 V, VDD = 5.0 V	tr	-	47.9	-	
	V		_			7

#### Turn-Off Delay Time ID = 0.1 A, RG = $50\Omega$ ) Fall Time

S	SOURCE-DRAIN DIODE CHARACTERISTICS					
	Forward Voltage	VSD				V
	(VGS = 0 V, ISD = 10 mA)		-	0.65	0.7	
	Reverse Recovery Time	trr				ns
	$(VGS = 0 V,dIS/dt = 8A/\mu s,IS = 10 mA)$		-	14	-	

td(off)

tf

65.1

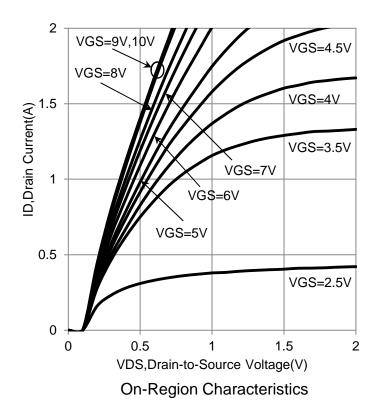
64.2

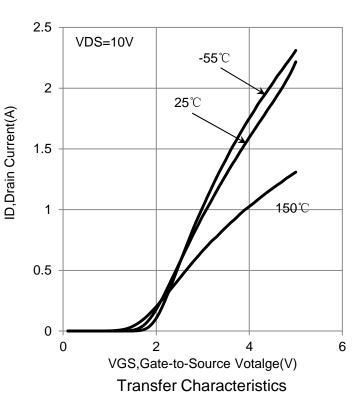
Leshan Radio Company, LTD. Rev.B Mar 2016 2/5

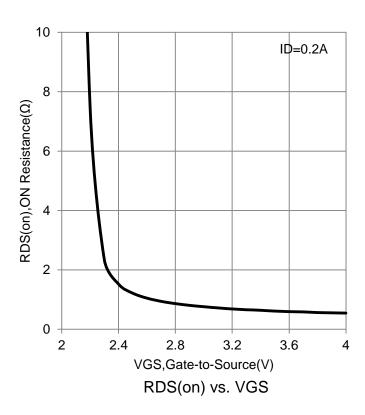
<sup>1.</sup> Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).

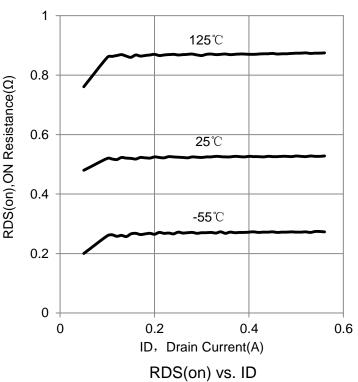
<sup>2.</sup> Pulse Test: Pulse Width ≤300  $\mu$ s, Duty Cycle ≤2.0%.

## 7. ELECTRICAL CHARACTERISTICS CURVES

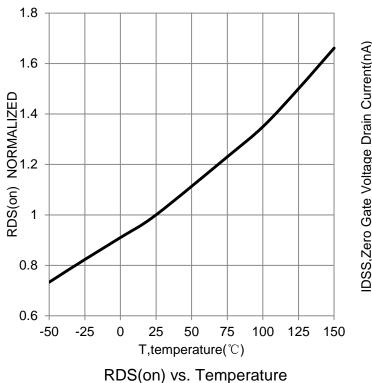


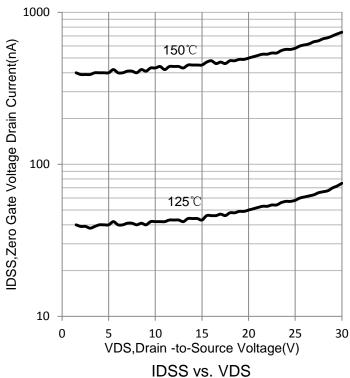


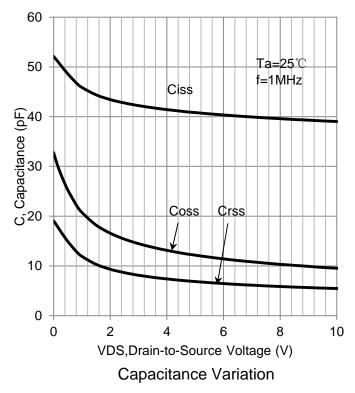


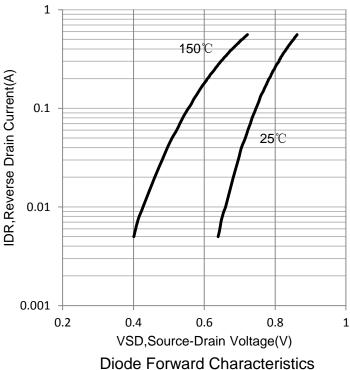


## 7. ELECTRICAL CHARACTERISTICS CURVES (Con.)



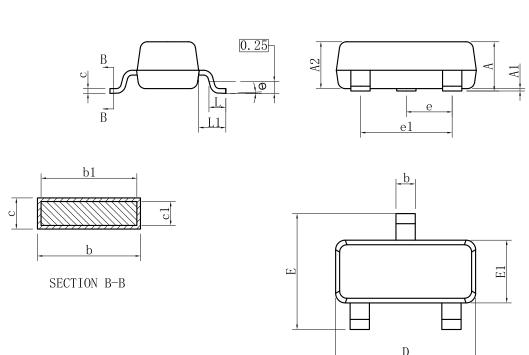






30 V, 0.56 A, Single, N-Channel, Gate ESD Protection, SOT-23

# **8.OUTLINE AND DIMENSIONS**

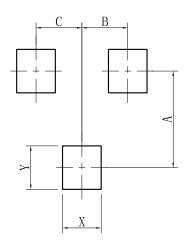


SOT23				
DIM	MIN	NOR	MAX	
A	0.89	-	1.12	
A1	0.01	ı	0.10	
A2	0.88	0.95	1.02	
b	0.30	ı	0.50	
b1	0.30	0.40	0.45	
С	0.08	ı	0.20	
c1	0.08	0.10	0.16	
D	2.80	2.90	3.04	
Е	2.10	ı	2.64	
E1	1.20	1.30	1.40	
е	0.00000			
e1	1. 90BSC			
L	0.40	0.46	0.60	
L1		0.54REF	ì	
θ	0°	-	8°	
All Dimensions in mm				

#### GENERAL NOTES

- 1. Top package surface finish Ra0.4 $\pm$ 0.2um
- 2. Bottom package surface finish RaO.7 $\pm$ 0.2um
- 3. Side package surface finish RaO.4 $\pm$ 0.2um

## 9.SOLDERING FOOTPRINT



SOT23				
DIM	(mm)			
X	0.80			
Y	0.90			
A	2.00			
В	0.95			
С	0.95			



#### **DISCLAIMER**

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee. The curve of test items without electric parameter is used as reference only.
- Before you use our Products for new Project, you are requested to carefully read this document and fully understand its contents. LRC shall not be in any way responsible or liable for failure, malfunction or accident arising from the use of any LRC's Products against warning, caution or note contained in this document.
- All information contained in this document is current as of the issuing date and subject to change without any prior notice. Before purchasing or using LRC's Products, please confirm the latest information with a LRC sales represe--ntative.